

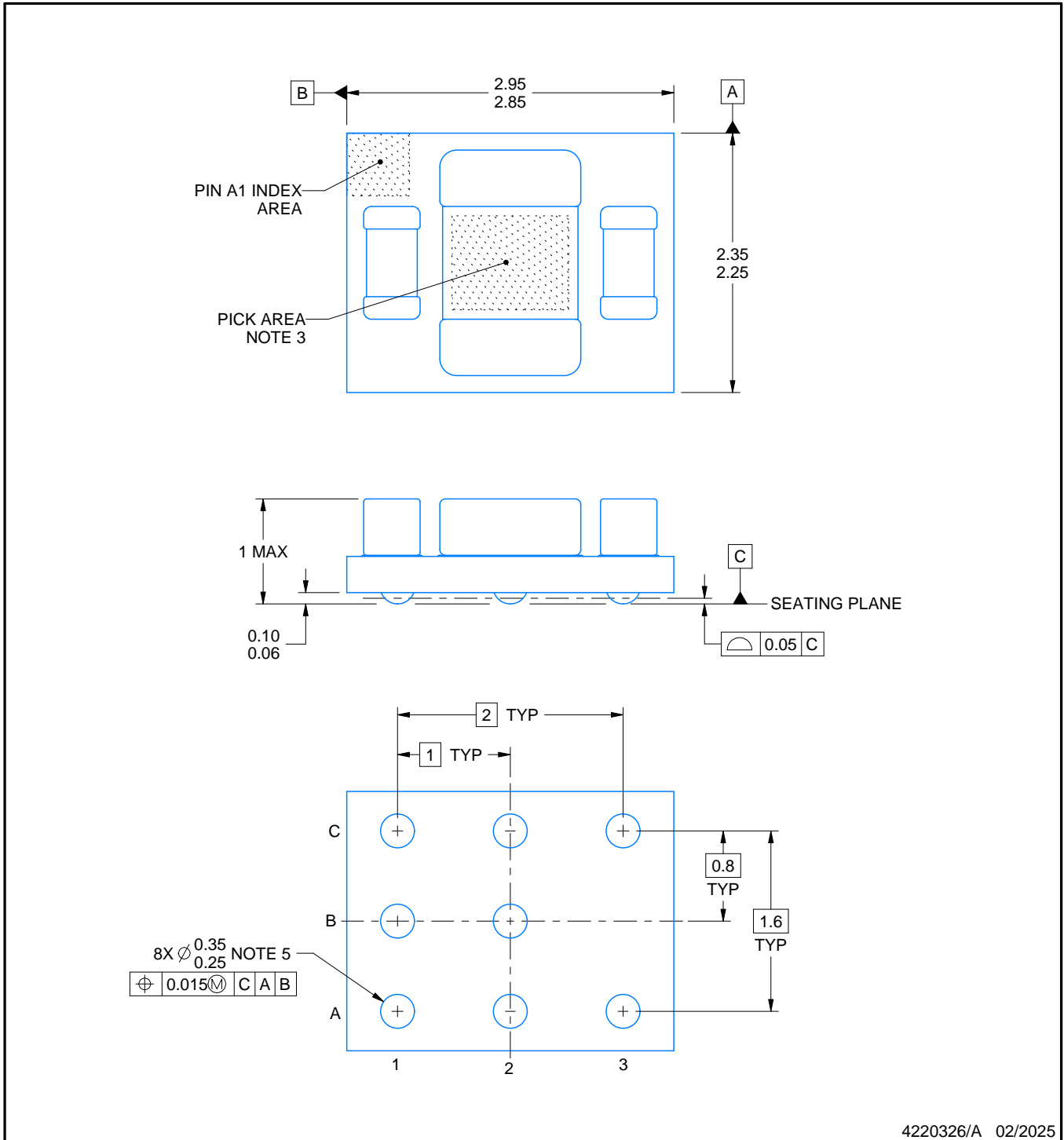


# PACKAGE OUTLINE

## SIP0008A

### MicroSiP™ - 1 mm max height

MICRO SYSTEM IN PACKAGE



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MicroSiP is a trademark of Texas Instruments.

#### NOTES:

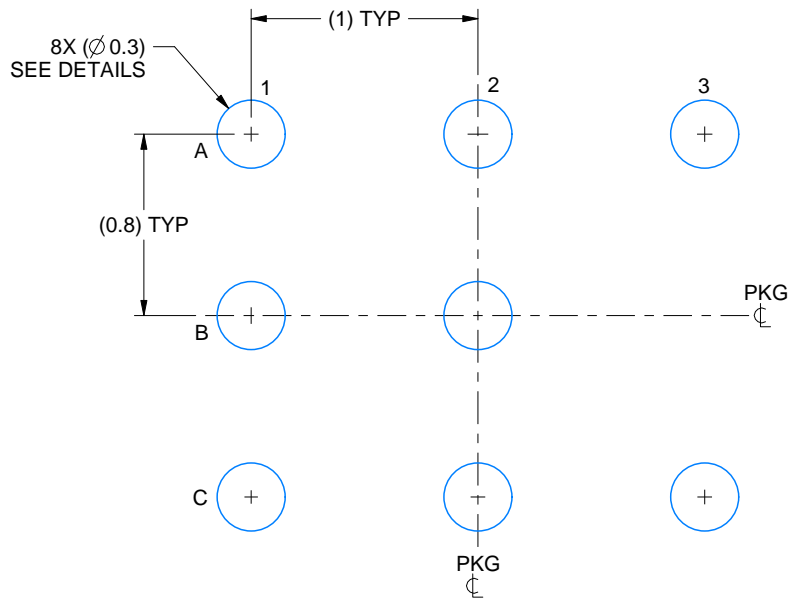
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. For pick and place nozzle recommendation, see product datasheet.
4. Location, size and quantity of each component are for reference only and may vary.
5. This package contains Pb-free balls.

# EXAMPLE BOARD LAYOUT

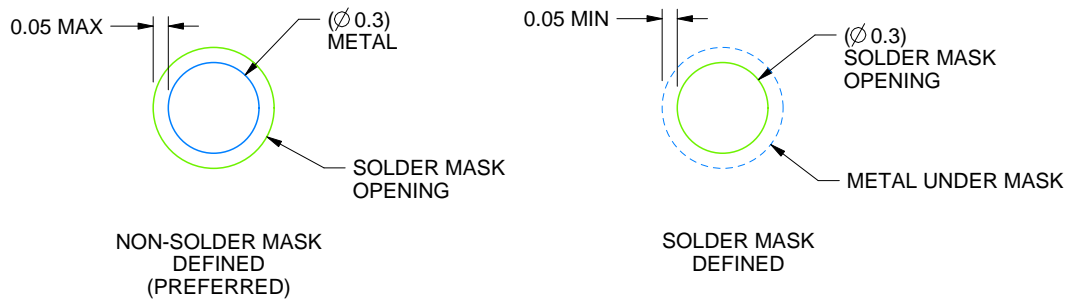
SIP0008A

MicroSiP™ - 1 mm max height

MICRO SYSTEM IN PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 30X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

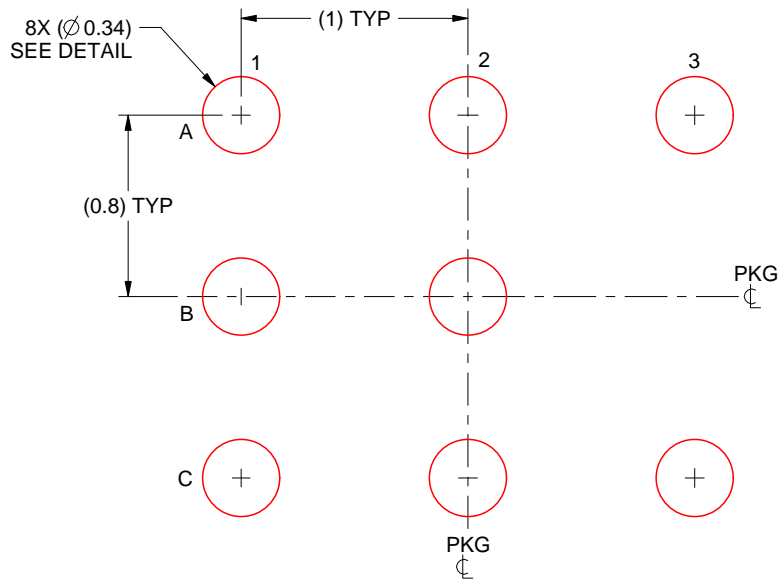
6. For more information, see Texas Instruments literature number SBVA017 ([www.ti.com/lit/sbva017](http://www.ti.com/lit/sbva017)).

# EXAMPLE STENCIL DESIGN

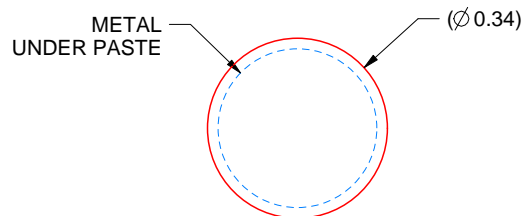
SIP0008A

MicroSiP™ - 1 mm max height

MICRO SYSTEM IN PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X



SOLDER PASTE DETAIL  
TYPICAL

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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